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EBEAM INITIATIVE MEMBER COMPANIES TO TAKE CENTER STAGE AT SPIE ADVANCED LITHOGRAPHY AND PATTERNING CONFERENCE

Member participation includes eight keynotes and nearly 300 presentations; live member event to provide insight on lithography and photomask trends

SAN JOSE, Calif., February 18, 2025—The eBeam Initiative, a forum dedicated to the education and promotion of new semiconductor manufacturing approaches based on electron beam (eBeam) technologies, today announced it will host the 16th annual eBeam Initiative lunch meeting and celebrate nearly 300 presentations by its member companies at the SPIE Advanced Lithography and Patterning Conference (SPIE-AL+P), taking place next week in San Jose, Calif., February 23-27.

At SPIE-AL+P 2025, eBeam Initiative members will deliver eight keynote addresses and co-author nearly 300 presentations – more than half of the total number of program talks – on a variety of topics critical to the future success of semiconductor manufacturing, including high-NA and hyper-NA EUV, curvilinear designs, multi-beam mask writing, nanoimprint, deep learning, and sustainability. In the years since its founding in 2009 with 20 members, the eBeam Initiative has expanded its membership to include more than 50 member companies across the semiconductor manufacturing and design ecosystem, including many of the world's preeminent technology innovators and market leaders.

The eBeam Initiative also announces the publication of its fifth annual Deep Learning (DL) survey of its members' products and applications using DL in the photomask-to-wafer manufacturing flow. The complete list of DL applications from 17 member companies can be found at www.ebeam.org.

Logos of current eBeam Initiative member companies and design advisory team. Source: eBeam Initiative.

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The eBeam Initiative will also host its 16th annual lunch meeting during SPIE-AL+P, featuring two invited talks: one from Dr. Frank Abboud of Intel on large format masks and their productivity benefits, and one from Aki Fujimura of D2S on improving uniformity and linearity for photomasks using multi-beam mask writers, GPU acceleration and pixel-based computing. Attendees of this sought-after event will include eBeam Initiative members, industry luminaries, and press and analysts.

According to Jan Willis, co-founder of the eBeam Initiative, "Every year, SPIE-AL+P brings together the lithography industry, academia and community to solve challenges in optical and EUV lithography, patterning technologies, metrology, and process integration for semiconductor manufacturing. We congratulate eBeam Initiative members on their contributions to the conference and for supporting our educational goals, including the adoption trend for deep learning applications in semiconductor manufacturing."

About The eBeam Initiative
The eBeam Initiative provides a forum for educational and promotional activities regarding new semiconductor manufacturing approaches based on electron beam (eBeam) technologies. The goals of the Initiative are to reduce the barriers to adoption to enable more integrated circuit (IC) design starts and faster time-to-market while increasing the investment in eBeam technologies throughout the semiconductor ecosystem. Members, which span the semiconductor ecosystem, include: aBeam Technologies; Advantest; Alchip Technologies; AMD; AMTC; Applied Materials; Artwork Conversion; ASML; Averroes.ai; Cadence Design Systems; Canon; CEA-Leti; D2S; Dai Nippon Printing; EQUIcon Software GmbH Jena; ESOL; EUV Tech; Fractilia; Fraunhofer IPMS; FUJIFILM Corporation; Fujitsu Semiconductor Limited; GenISys GmbH; GlobalFoundries (GF); Grenon Consulting; Hitachi High-Tech Corporation; HJL Lithography; HOLON CO., LTD; HOYA Corporation; IBM; imec; IMS CHIPS; IMS Nanofabrication AG; JEOL; KIOXIA; KLA; Micron Technology; Multibeam Corporation; NCS; NuFlare Technology; Petersen Advanced Lithography; Photronics; QY Mask; Samsung Electronics; Semiconductor Manufacturing International (Shanghai) Corporation (SMIC); Siemens EDA; STMicroelectronics; Synopsys; TASMIT; Tokyo Electron Ltd. (TEL); TOOL Corporation; Tekscend Photomask; UBC Microelectronics; Vistec Electron Beam GmbH and ZEISS. Membership is open to all companies and institutions throughout the electronics industry. To find out more, please visit www.ebeam.org.

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